



e-Manufacturing Symposium 2007



Thursday June 14, 2007, Taipei, Taiwan, ROC

— A Joint Symposium with *Automation 2007*

Extension Announcement

In response to requests, the Organizing Committee has decided to extend the submission deadline to **Friday March 9, 2007** so as to reflect the latest developments on the front of e-Manufacturing.

Call for Papers

Organizers —

Taiwan Semiconductor Industry Association
SEMI Taiwan
IEEE-RAS Technical Committee on Semiconductor Factory Automation
Society of Manufacturing Engineers (Taipei Chapter)
Chinese Institute of Automation Engineers
National Formosa University

Date — Thursday June 14, 2007

Venue — The Howard Plaza Hotel Taipei, Taipei, Taiwan

Sponsor —

IEEE Robotics and Automation Society
(Taipei Chapter)

Steering Committee —

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Mr. Thomas Chen, Director, TSID/tsmc
Mr. William Yuan, CIO, PSC
Prof. MuDer Jeng, NTOU
Ms. Irene Yu, Director, SEMI Taiwan

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Student Paper Competition —

Coordinator — Dr. C. Hsu (tsmc)

Theme —

The Semiconductor Industry has undergone drastic transformations in recent years. Driven by the sudden expansion of manufacturing capacities worldwide in 300mm wafers, and coupled by the rapid evolution of manufacturing capabilities in full-scale functional integrations from shop-floors up to top-level corporate operations, this transformation is in constant acceleration to accompany the stringent technological requirements of ever-shrinking device dimensions, so as to meet the unquenchable thirst of human demands on all digital inventions, large or small. The sky-high investment in each 300-mm wafer fabrication plant places too huge a financial stack for any business operator taking risks not to integrate every functionality and activity under one single synchronized note in order to cut down costs and reduce cycle-times while staying flexible to respond immediately to market changes.

Scope —

With all the prevailing notions of supply-chains, engineering-chains, value-chains and many others as ascribed, e-Manufacturing has been identified to unify the synchronized integration as a critical link in these chains. To drive in recognition of e-Manufacturing in Semiconductor Manufacturing Industry with specific concerns targeted to the interests of manufacturers in the region, Taiwan Semiconductor Industry Association (TSIA) initiates **e-Manufacturing Symposium 2007**, in joint efforts with **Automation 2007**. This offers a public arena facilitating exchanges of up-to-date experiences among Asian manufacturers for adoption of recent technological developments in e-Manufacturing.

This Call for Papers is directed towards all industries but flavour from the semiconductor community is highly encouraged. Recent advancements are reviewed to align the needs of device makers, suppliers and vendors alike.

Contributions from academic studies and industrial practices are welcome. Papers with new research and/or application results in all aspects of e-Manufacturing are encouraged to submit. Topics of interests include, but not limited to, the following:

- Automated Material Handling System
- Data Collection
- Data Quality
- Design for Manufacturing
- e-Diagnostics
- Engineering Chains
- Equipment Communication
- Equipment Integration
- Factory Integration
- Factory Operations
- Fault Detection & Classification
- Integrated Metrology
- Maintenance
- Manufacturing Execution Systems
- Real-Time Decision-Making
- Run to Run Control
- Scheduling & Dispatching
- Specification Management
- Supply Chains
- Value Chains
- WIP Management

Submission Procedure —

Electronic submission of full-length paper in MSWord or PDF format must be made by **March 9, 2007** directly to eManufacturing@tsia.org.tw. You should select the topic(s) your contribution best fits in from the list above.

Each paper (up to a maximum of six-pages of A4-paper size at two-column formats with 10-point fonts, including both texts and graphical illustrations) should clearly describe the purpose, the chosen approach, and the achieved results.

Presentations may be conducted in oral or interactive-poster formats. You may indicate your preference of oral or poster presentation, and the program committee will decide the final selection of oral presentations. Presenters will be notified by **April 1, 2007** and final PowerPoint presentations must be submitted by **May 15, 2007** in electronic format. Official language of the symposium is English.

All submissions must include:	
Title of Paper	
Author's name(s), address and affiliation(s)	
Contact telephone/fax numbers	
E-mail address	
Presenter's name	
Five keywords	

First announcement	May 1, 2006
Second announcement	November 1, 2006
Third announcement	February 1, 2007
Deadline of Submission	March 9, 2007
Notification of acceptance	April 1, 2007
Final papers due	May 15, 2007
Deadline for pre-registration	May 15, 2007
On site registration	June 14, 2007